

3E	0.2 wt.% tetraethylenepentamine	0.21	0.13
3F	0.2 wt.% N,N,N',N'-tetramethyl- 1,4-butanediamine	-	0.37
3G	0.5 wt.% propylamine	0.17	-
3H	0.2 wt.% 2-(2- aminoethoxy) ethanol 2-(2-aminoethoxy)ethanol	0.71	-
3I	3.0 wt.% 2-amino-1-butanol	0.04	0.21
3J	0.2 wt.% 4,7,10-trioxa- 1,13-tridecanediamine	0.28	0.22
3K	0.2 wt.% lysine	0.35	1.1
3L	0.2 wt.% poly[bis(2-chloroether)- alt-1,3-bis(3- dimethylamino)propyl] poly[bis(2-chloroether)-alt-1,3- bis(3-dimethylamino)propyl]	-	0.33

Amendments to existing claims:

9. (Amended) The system of claim 7, wherein at least one stopping compound is selected from the group consisting of a polyetheramine, polyethylenimine, ~~N₄-amin~~ (N,N'-bis-[3-aminopropyl]ethylene-diamine) ~~N₄-amino(N,N'-bis-[3-aminopropyl]ethylenediamine)~~, 4,7,10-trioxatridecane-1,13-diamine, 3,3-dimethyl-4,4-diaminodicyclohexylmethane, 2-phenylethylamine, N,N-dimethyldipropylenetriamine, 3-[2-methoxyethoxy]propylamine, dimethylaminopropylamine, ~~1,4-bis(3-amino-propyl)-piperazine~~ 1,4-bis(3-aminopropyl)piperazine, and mixtures thereof.

10. (Amended) The system of claim 7, wherein the stopping compound is selected from the group consisting of ~~isophorone diamine~~ isophoronediamine, hexamethylenediamine, cyclohexyl-1,3-~~propane diamine~~ propanediamine, thiomicamine, (aminopropyl)-1,3-~~propane diamine~~ propanediamine, tetraethylenepentamine, tetramethylbutanediamine, propylamine, diaminopropanol, aminobutanol, (2-aminoethoxy)ethanol, ~~or~~ and mixtures thereof.

23. (Amended) The system of claim 16, wherein at least one stopping compound comprises an ~~amino-propyl~~ aminopropyl group.

25. (Amended) The system of claim 3, wherein the system comprises a peroxide, aminotri(methylenephosphonic acid), and ~~1,4-bis(3-amino-propyl)-piperazine~~ 1,4-bis(3-aminopropyl)piperazine.

43. (Amended) The composition of claim 38, wherein at least one stopping compound comprises an ~~amino-propyl~~ aminopropyl group.

The following claims are added:

45. (New) The method of claim 33, wherein the first metal layer comprises copper, aluminum, titanium, tungsten, platinum, ruthenium, iridium, and combinations thereof.

46. (New) The method of claim 33, wherein the first metal layer is platinum, ruthenium, or iridium and the stopping compound is a polyethylenimine.

47. (New) The system of claim 16, wherein at least one polishing additive is selected from poly-carboxylic acids.

48. (New) The system of claim 16, wherein at least one stopping compound is a polyetheramine.

49. (New) The system of claim 16, wherein at least one oxidizing agent is a peroxide, and wherein the system further comprises at least one passivation film forming agent comprising one or more 5-6 member heterocyclic nitrogen-containing rings.

50. (New) The system of claim 24, wherein at least one polishing additive is selected from poly-carboxylic acids.

51. (New) The system of claim 1, wherein at least one polishing additive is a carboxylic acid and at least one stopping compound has a molecular weight of about 250 or more.